

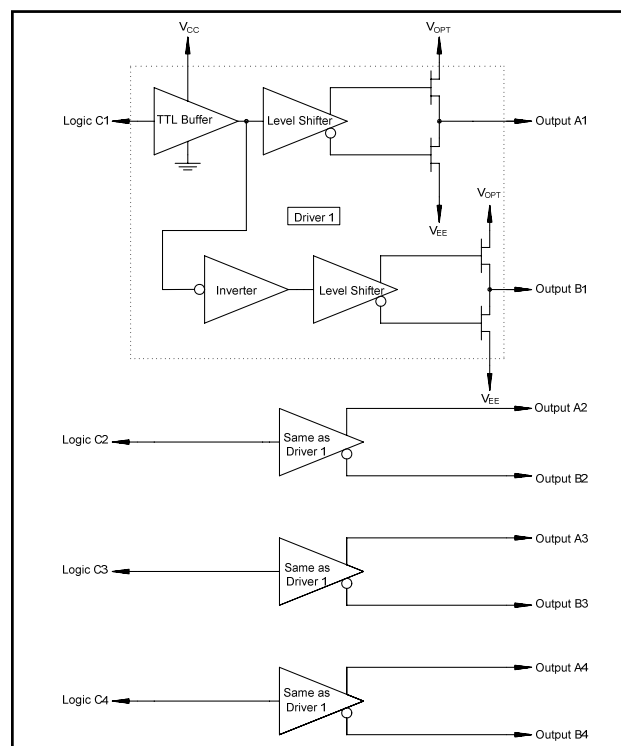
### Features

- High Voltage CMOS Technology
- Four Channel
- Positive Voltage Control
- CMOS device using TTL input levels
- Low Power Dissipation
- Low Cost Lead-Free SOIC-16 Plastic Package
- Halogen-Free “Green” Mold Compound
- RoHS\* Compliant and 260°C Reflow Compatible

### Description

The MADR-009190-000100 is a four channel driver used to translate TTL control inputs into gate control voltages for GaAs FET microwave switches and attenuators. High speed analog CMOS technology is utilized to achieve low power dissipation at moderate to high speeds, encompassing most microwave switching applications. The output HIGH level is optionally 0 to +2.0V (relative to GND) to optimize the intermodulation products of FET control devices at low frequencies. For driving PIN Diode circuits, the outputs are nominally switched between +5V & -5V. The actual driver output voltages will be lower when driving large currents due to the resistance of the output devices.

### Functional Schematic



### Ordering Information<sup>1</sup>

Part Number	Package
MADR-009190-000100	Bulk Packaging
MADR-009190-000DIE	Die <sup>2</sup>
MADR-009190-0001TR	1000 piece reel

1. Reference Application Note M513 for reel size information.
2. Die sales are available in waffle packs in increments of 100 pieces.

### Pin Configuration<sup>3</sup>

Pin No.	Function	Pin No.	Function
1	V <sub>EE</sub>	9	Output A1
2	V <sub>CC</sub>	10	Output B1
3	C4	11	Output A2
4	C3	12	Output B2
5	C2	13	Output A3
6	C1	14	Output B3
7	V <sub>OPT</sub>	15	Output A4
8	Ground	16	Output B4

3. The bottom of the die should be isolated for part number MADR-009190-000DIE.

\* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

### Guaranteed Operating Ranges (for driving FET or PIN devices) <sup>4,5,8</sup>

Symbol	Parameter	Unit	Min.	Typ.	Max.
$V_{CC}$	Positive DC Supply Voltage	V	4.5	5.0	5.5
$V_{EE}$	Negative DC Supply Voltage	V	-10.5	-5.0	-4.5
$V_{OPT}^{6,7}$	Optional DC Output Supply Voltage	V	0	—	$V_{CC}$
$V_{OPT} - V_{EE}$	Negative Supply Voltage Range	V	4.5	Note 6,7	16.0
$V_{CC} - V_{EE}$	Positive to negative Supply Range	V	9.0	10.0	16.0
$T_{OPER}$	Operating Temperature	°C	-40	+25	+85
$I_{OH}$	DC Output Current - High	mA	-35	—	—
$I_{OL}$	DC Output Current - Low	mA	—	—	35
$T_{rise}, T_{fall}$	Maximum Input Rise or Fall Time	ns	—	—	500

4. Unused logic inputs must be tied to either GND or  $V_{CC}$ .
5. All voltages are relative to GND.
6.  $V_{OPT}$  is grounded in most cases when FETs are driven. To improve the intermodulation performance and the 1 dB compression point of GaAs control devices at low frequencies,  $V_{OPT}$  can be increased to between 1.0 and 2.0V. The nonlinear characteristics of the GaAs control devices will approximate performance at 500 MHz. It should be noted that the control current that is on the GaAs MMICs will increase when positive controls are applied.
7. When this driver is used to drive PIN diodes,  $V_{OPT}$  is often set to +5.0V, with  $V_{EE}$  set to -5.0V.
8. 0.01 uF decoupling capacitors are required on the power supply lines.

### Handling Procedures

Please observe the following precautions to avoid damage:

### Static Sensitivity

Silicon Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

### Truth Table

Input	Outputs	
Cn	An	Bn
Logic "0"	$V_{EE}$	$V_{OPT}$
Logic "1"	$V_{OPT}$	$V_{EE}$

**DC Characteristics over Guaranteed Operating Range**

Symbol	Parameter	Test Conditions	Units	Min.	Typ.	Max.
$V_{IH}$	Input High Voltage	Guaranteed High Input Voltage	V	2.0	—	—
$V_{IL}$	Input Low Voltage	Guaranteed Low Input Voltage	V	—	—	0.8
$V_{OH}$	Output High Voltage	$I_{OH} = -0.5 \text{ mA}$	V	$V_{OPT} - 0.1$	—	—
$V_{OL}$	Output Low Voltage	$I_{OL} = 0.5 \text{ mA}$	V	—	—	$V_{EE} + 0.1$
$I_{IN}$	Input Leakage Current (per Input)	$V_{IN} = V_{CC}$ or GND, $V_{EE} = \text{min}$ , $V_{CC} = \text{max}$ , $V_{OPT} = \text{min or max}$	nA	-250	—	250
$I_{OH}$	DC Output Current—High (per Output)	$V_{CC} = 5.0\text{V}$ , $V_{EE} = -5.0\text{V}$ , $V_{OPT} = 5.0\text{V}$	mA	-35	—	—
$I_{OL}$	DC Output Current—Low (per Output)	$V_{CC} = 5.0\text{V}$ , $V_{EE} = -5.0\text{V}$ , $V_{OPT} = 5.0\text{V}$	mA	—	—	35
$I_{OH\_SPIKE}$	Peak Spike Output Current (Rising Edge) (per Output)	$V_{CC} = 5.0\text{V}$ , $V_{EE} = -5.0\text{V}$ , $V_{OPT} = 5.0\text{V}$ , $C_L = 25 \text{ pF}$	mA	—	35	—
$I_{OL\_SPIKE}$	Peak Spike Output Current (Falling Edge) (per Output)	$V_{CC} = 5.0\text{V}$ , $V_{EE} = -5.0\text{V}$ , $V_{OPT} = 5.0\text{V}$ , $C_L = 25 \text{ pF}$	mA	—	50	—
$I_{CC}$	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $V_{EE} = -10.5\text{V}$ , $V_{CC} = 5.5\text{V}$ , $V_{OPT} = 5.5\text{V}$ , No Output Load	$\mu\text{A}$	—	—	20
$\Delta I_{CC}$	Additional Supply Current (per TTL Input pin)	$V_{CC} = \text{max}$ , $V_{IN} = V_{CC} - 2.1\text{V}$	mA	—	—	1.0
$I_{EE}$	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $V_{EE} = -10.5\text{V}$ , $V_{CC} = 5.5\text{V}$ , $V_{OPT} = 5.5\text{V}$ , No Output Load	$\mu\text{A}$	—	—	20
$I_{OPT}$	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $V_{EE} = -10.5\text{V}$ , $V_{CC} = 5.5\text{V}$ , $V_{OPT} = 5.5\text{V}$ , No Output Load	$\mu\text{A}$	—	—	20
$R_{NFET}$	Output Resistance NFET On (to $V_{EE}$ )	$V_{CC} = 5.0\text{V}$ , $V_{EE} = -5.0\text{V}$ , $V_{OPT} = 5.0\text{V}$ , $V_{OUT} = -4.9\text{V}$ +25°C, Note 9	$\Omega$	—	40	—
$R_{PFET}$	Output Resistance PFET On (to $V_{OPT}$ )	$V_{CC} = 5.0\text{V}$ , $V_{EE} = -5.0\text{V}$ , $V_{OPT} = 5.0\text{V}$ , $V_{OUT} = 4.9\text{V}$ +25°C, Note 9	$\Omega$	—	45	—

9. See plot of  $R_{NFET}$  and  $R_{PFET}$  for variations over temperature for driving 4.99k and 82 ohm resistive load. (Note that this corresponds to 1 mA and 33 mA currents at 25°).

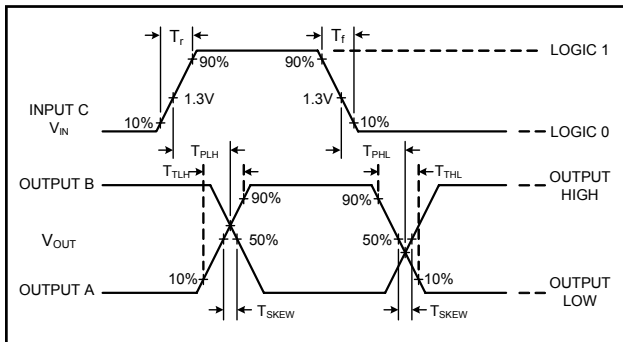
### AC Characteristics Over Guaranteed Operating Range <sup>10</sup>

Symbol	Parameter	Typical performance			Unit
		-40°C	+25°C	+85°C	
T <sub>PLH</sub>	Propagation Delay	20	22	25	ns
T <sub>PHL</sub>	Propagation Delay	20	22	25	ns
T <sub>TLH</sub>	Output Transition Time (Rising Edge)	5	6	8	ns
T <sub>THL</sub>	Output Transition Time (Falling Edge)	5	6	8	ns
T <sub>skew</sub>	Delay Skew	2	2	2	ns
PRF (max)	50% Duty Cycle	DC	—	10	MHz
C <sub>IN</sub>	Input Capacitance	5	5	5	pF
C <sub>PDC</sub>	Power Dissipation Capacitance <sup>11</sup>	50	50	50	pF
C <sub>PDE</sub>	Power Dissipation Capacitance <sup>11</sup>	100	100	100	pF

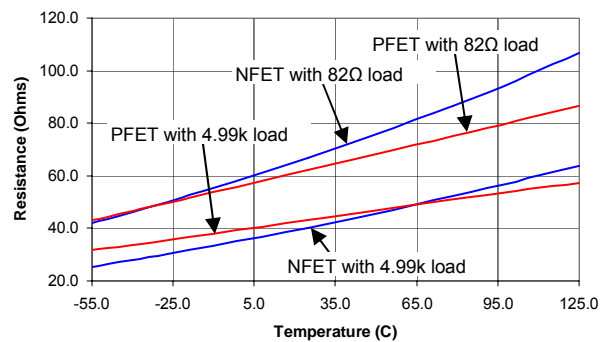
10. V<sub>CC</sub> = 4.5V, V<sub>OPT</sub> = 0V, V<sub>EE</sub> = min or max, C<sub>L</sub> = 25 pF, input LOGIC1 = 3V, LOGIC0 = 0V, Trise, Tfall = 6 ns.

11. Total Power Dissipation is calculated by the following formula: PD = V<sub>CC</sub><sup>2</sup>fC<sub>PDC</sub> + V<sub>EE</sub><sup>2</sup>fC<sub>PDE</sub>

### Switching Waveforms



### Output Resistance vs. Temperature <sup>12</sup>



12. Output resistance were measured under the condition of V<sub>CC</sub> = 5.0V, V<sub>OPT</sub> = 5.0V, and V<sub>EE</sub> = -5.0V, with load resistors from outputs to ground.

### Absolute Maximum Ratings<sup>13</sup>

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Positive DC Supply Voltage	-0.5	7.0	V
$I_{CC}$	Positive DC Supply Current ( $-0.5V \leq V_{IN} \leq 0.8V$ ; $2.0V \leq V_{IN} \leq V_{CC} + 0.5V$ ; $V_{CC} - V_{IN} \leq 7.0V$ )	—	20	mA
$V_{EE}$	Negative DC Supply Voltage	-11.0	0.5	V
$I_{EE}$	Negative DC Supply Current (per Output) <sup>14</sup>	-50	—	mA
$V_{OPT}$	Optional DC Output Supply Voltage	-0.5	$V_{CC} + 0.5$	V
$I_{OPT}$	Optional DC Output Supply Current (per Output) <sup>14</sup>	—	50	V
$V_{OPT} - V_{EE}$	Output to Negative Supply Voltage Range	-0.5	18.0	V
$V_{CC} - V_{EE}$	Positive to Negative Supply Voltage Range	-0.5	18.0	V
$V_{IN}$	DC Input Voltage	-0.5 Note 15	$V_{CC} + 0.5$	V
$V_O$	DC Output Voltage	$V_{EE} - 0.5$	$V_{OPT} + 0.5$	V
$P_D$ <sup>16</sup>	Power Dissipation in Still Air	—	500	mW
$T_{OPER}$	Operating Temperature	-55	125	°C
$T_{STG}$	Storage Temperature	-65	150	°C
ESD	ESD Sensitivity	2.0	—	kV

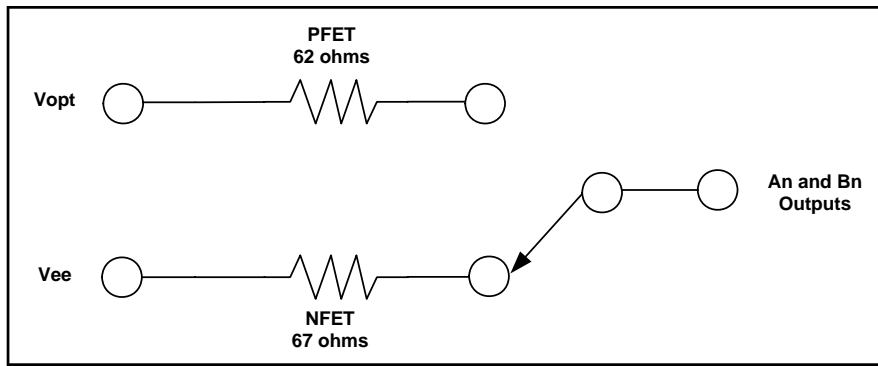
13. All voltages are referenced to GND. All inputs and outputs incorporate latch-up protection structures.

14. The maximum  $I_{EE}$  and  $I_{OPT}$  are specified under the condition of  $V_{CC} = 5.5V$ ,  $V_{EE} = -5.5V$ ,  $V_{OPT} = 5.5V$ , and the total power dissipation is within 500 mW in still air.

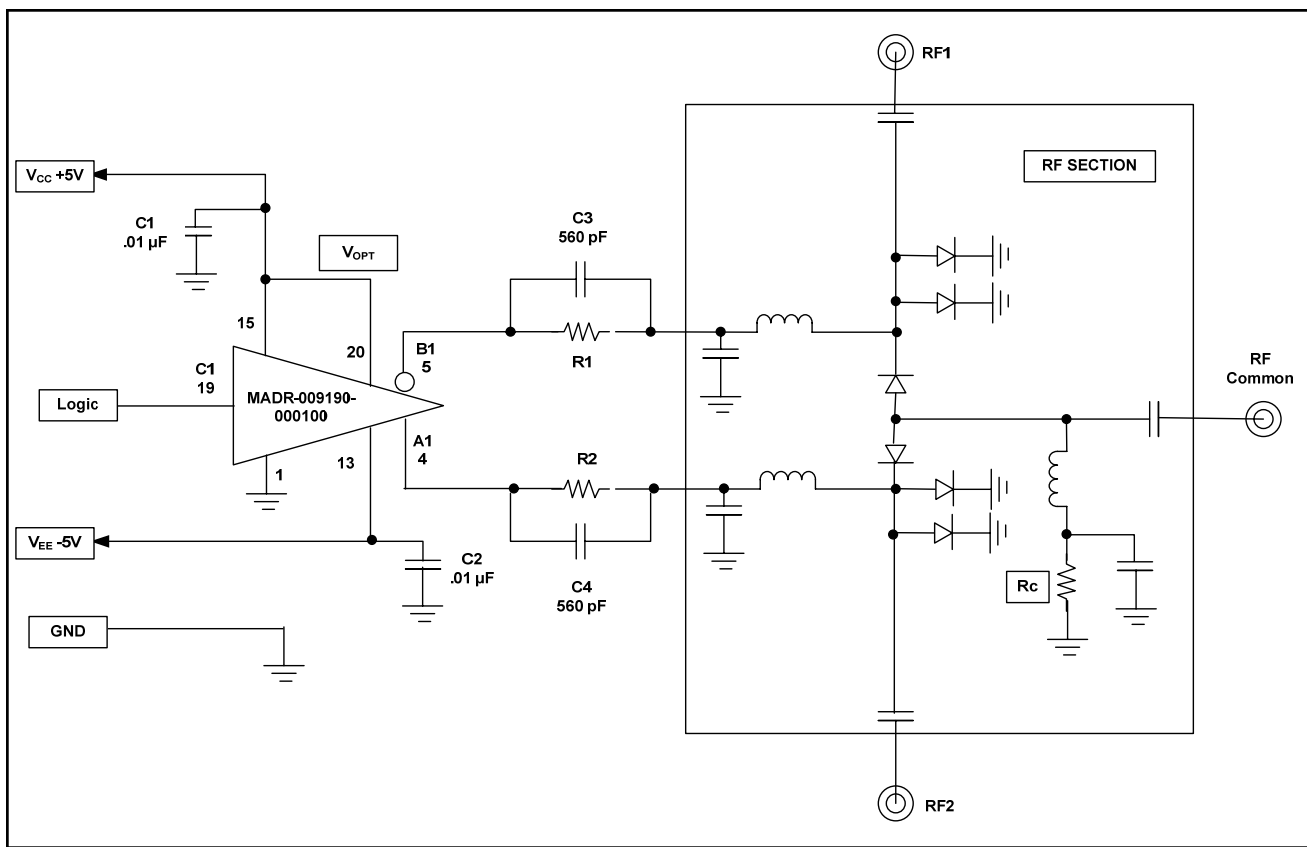
15. If  $V_{CC} \geq 6.5V$ , then the minimum for  $V_{IN}$  is  $V_{CC} - 7.0V$ .

16. Derate -7 mW/°C from 65°C to 85°C.

### Equivalent Output Circuit for An and Bn Outputs (33 mA load at 25°)



### Typical Application for a SPDT Switch <sup>17,18</sup>



17. Note that the description of the above circuit is on the following page.

18. Only one section of MADR-009190-000100 is shown. The other three sections will have equivalent performance.

## Quad Driver for GaAs FET or PIN Diode Switches and Attenuators

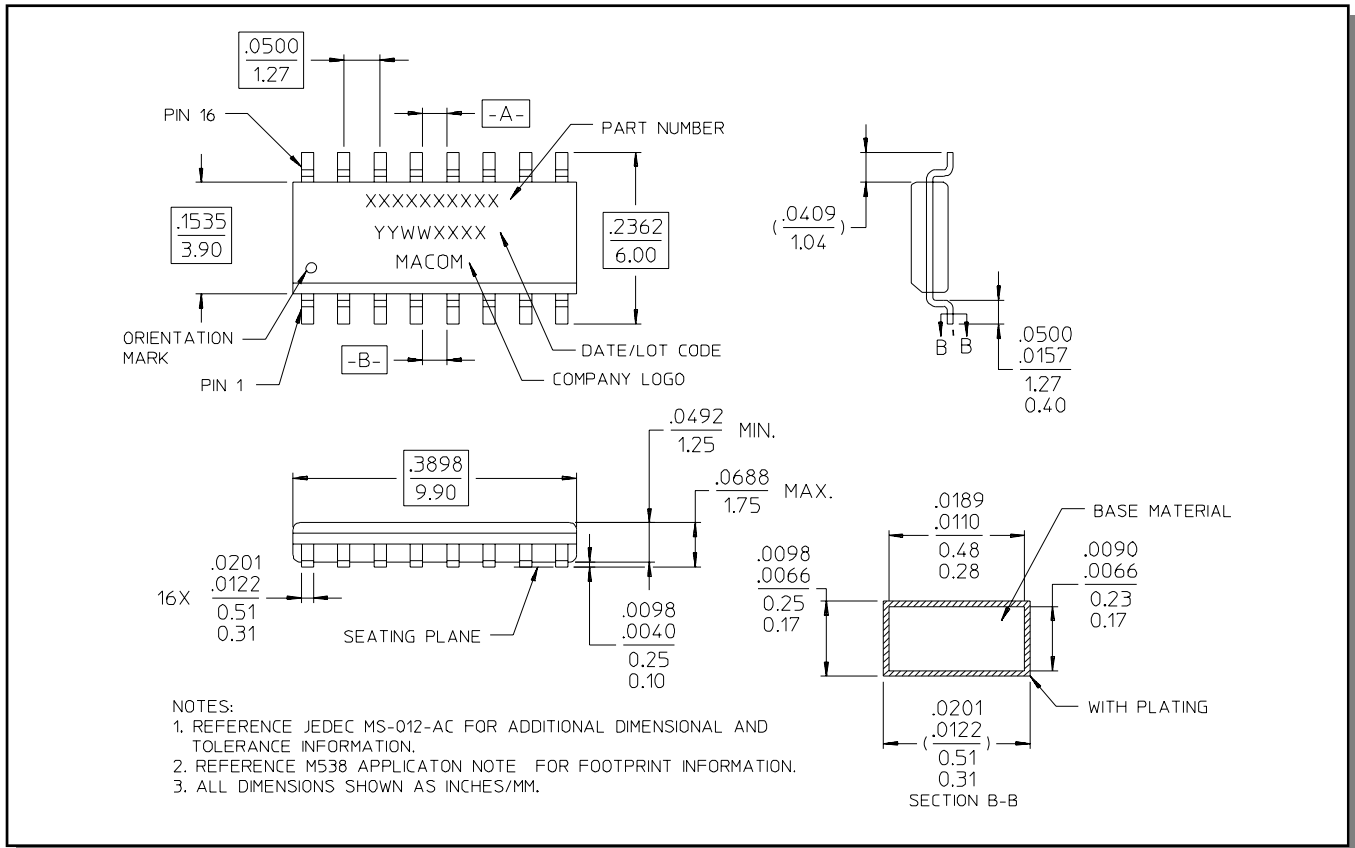
Rev. 4

### Description of Circuit

The MADR-009190-000100 provides four pairs of complementary outputs that are each capable of driving a maximum of  $\pm 35$  mA into a load. In addition, with proper capacitor selection (C3 & C4) used in parallel with the current setting resistor (R1 & R2), additional spiking current can be achieved.

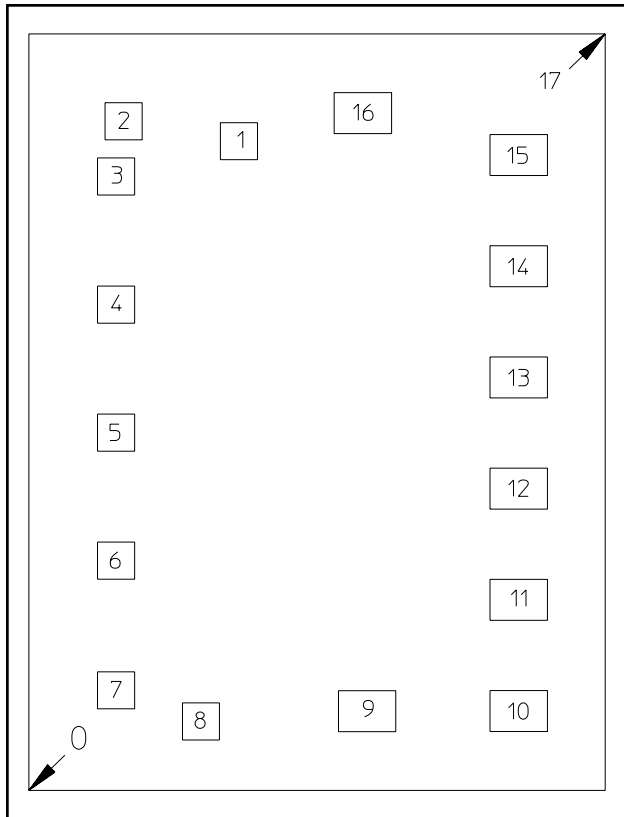
To achieve the Non-Inverting and Inverting complementary voltages, each output is switched between two internal FETs. The FETs are connected to  $V_{OPT}$  for the positive output and  $V_{EE}$  for the negative output.  $V_{OPT}$  and  $V_{EE}$  are adjustable for various configurations and have the following limitations:  $V_{EE}$  can be no more negative than  $-10.5$  volts;  $V_{OPT}$  can be no more positive than  $+5.5$  volts AND  $V_{OPT}$  must always be less than or equal to  $V_{CC}$ . Increasing  $V_{OPT}$  beyond  $V_{CC}$  will prevent the device from switching states when commanded to by the logic input. The most common configuration is to drive  $V_{EE}$  at  $-5.0$  volts with  $V_{CC}$  and  $V_{OPT}$  tied together at  $+5.0$  volts.

### Lead-Free, SOIC-16<sup>†</sup>



<sup>†</sup> Reference Application Note M538 for lead-free solder reflow recommendations. Plating is 100% matte tin over copper.

### Die Outline



### Pad Configuration<sup>19,20</sup>

Die Size: 1325 x 1735  $\mu\text{m}$  (nominal)

Pad No.	X ( $\mu\text{m}$ ) nominal	Y ( $\mu\text{m}$ ) nominal	Pad Size ( $\mu\text{m}$ ) X x Y
0	0	0	Lower left edge of die
1	482.95	1489	85 x 85
2	217.85	1534.6	85 x 85
3	200.45	1407.9	85 x 85
4	200.45	1114.2	85 x 85
5	200.45	820.45	85 x 85
6	200.45	526.8	85 x 85
7	200.45	229.35	85 x 85
8	395.6	157.95	85 x 85
9	777.55	181.5	132 x 94
10	1126.35	181.75	132 x 94
11	1126.35	436.85	132 x 94
12	1126.35	691.95	132 x 94
13	1126.35	947.05	132 x 94
14	1126.35	1202.15	132 x 94
15	1126.35	1457.3	132 x 94
16	767.9	1553.5	132 x 94
17	1325	1735	Upper right edge of die

19. All X,Y dimensions are at bond pad center.  
20. Die thickness is 8.0 mils.